# AGATA at GSI Infrastructure Issues

- Overview of Infrastructure
- Detector Support System and Front End Electronics:
  - Detector supplies & location
  - Digitiser location
  - Cryogenics and location
  - Services (power, UPS, etc.)
- Grounding
- Preprocessing electronics location and connection to
- DAQ / computing
- Summary

#### **Overview of Infrastructure**









### **Location Constraints**



- Detector supplies & location
- Digitiser location
- Cryogenics and location
- Services (power, UPS, etc.)

#### Detector supplies & location





#### LV:

1 PSU powers 1 ATC + Digitiser (4U, 47kg) 10A, air cooled ~15m cables to detector/digit 2mV ripple (good ground) **HV:** 

Currenly CAEN supply or cable **Detector:** 

Temp, LN2, etc.

#### **Digitiser** location





#### Digitiser:

1 digitisers connected to 1 crystal via 6 MDR cable 3 digitiser per ATC ~3U, 55kg

<10m from detector (copper) <50m from preproc (fibre)

Cooling: 1.5-2 bar, few l/min

#### **Cryogenics and location**







Cryogenic supply to area Buffer tanks 2 x 8 manifold





#### Services (power, UPS, etc.)





Figure 18.22: Draft of Demonstrator cabling at Legnaro

#### Four UPS units are to be provided by the H. Labs for

- the low-bias power supplies (including HV), the autofill, the associated slowcontrol systems and the front-end electronics (Digitiser modules)
- the pre-processing electronics
- the DAQ computers (PSA farms, event builder, tracking farm and data servers)
- the detector laboratory

Alarms Networking







UPS FILTER

AGATA PROJECT

EMC and GROUNDING

REPORT ON THE EMC EXPERTISE TESTS HELD @ PADOUA ON 08/07/2009

By: N. KARKOUR, A. CHAROY, A. RICHARD and M. TRIPON

# Grounding

#### THE GROUNDING



SOME WORK IS ALSO NEEDED ON THE DETECTORS



COPPER BARS AND WIRES



Take paint off and connect with large copper foil to the structure



Use a large copper to connect the 2 structures the width should be larger than the length.

- The whole array is grounded to a common voltage
- The common voltage is provided by a large common conductive plate
- The array itself is formed from interconnected conductive components using as short and thick grounding shunts as possible
- The ground of every component of the AGATA array, especially electronic devices, is grounded to the common voltage
- The power distribution to the front-end of the array is insured via a single uninterruptible power supply

#### 18.13.1.EMC performance

- AGATA front-end EMC performance is to be measured at both the low and the high frequencies.
- $\bullet$  The 50Hz noise is to be less than 100  $\mu V$  rms.
- The high-frequency noise in a range 100 kHz 100 MHz is to be less than 5mV maximum amplitude.

# Preprocessing electronics location and connection to







# DAQ / computing





Network connection from PP Currently 1 box / crystal Network connections Storage

#### THE LNL TIER ROOM

# Summary





